

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0	1.44	0.08
	Doped silicon	Silicon (Si)	7440-21-3	0.27	98.56	5.32
<b>Subtotal</b>				<b>0.27</b>	<b>100</b>	<b>5.4</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02	10.0	0.36
	Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.07
	Lead alloy	Lead (Pb)	7439-92-1	0.16	88.0	3.13
<b>Subtotal</b>				<b>0.18</b>	<b>100</b>	<b>3.56</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.41	100.0	8.16
	<b>Subtotal</b>				<b>0.41</b>	<b>100</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.4
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.06	0.8
	Copper alloy	Copper (Cu)	7440-50-8	66.98	99.91	1338.79
<b>Subtotal</b>				<b>67.04</b>	<b>100</b>	<b>1339.99</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.03	100.0	20.68
	<b>Subtotal</b>				<b>1.03</b>	<b>100</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.4	4.5	27.95
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.11	10.0	62.1
	Filler	Silica fused	60676-86-0	23.3	75.0	465.75
	Metal hydroxide	Metal hydroxide		3.11	10.0	62.1
	Carbon Black	Carbon black	1333-86-4	0.16	0.5	3.1
<b>Subtotal</b>				<b>31.08</b>	<b>100</b>	<b>621</b>
<b>Total</b>				<b>100.01</b>	<b>100</b>	<b>1998.79</b>

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